

Appl. No. 10/664,585
Amdt. Dated July 14, 2005
Reply to Office Action of April 15, 2005

Attorney Docket No. 81751.0066
Customer No. 26021

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended): A semiconductor device comprising:

~~an inner lead having a sloping section sloping upward and outward;~~
a die pad;
a semiconductor chip having an electrode and bonded to the die pad;
an inner lead having a sloping section sloping upward and outward,
when a surface of the die pad which the semiconductor chip is bonded faces
upward;
a wire electrically connecting the inner lead to the electrode;
a sealing section sealing the inner lead, the semiconductor chip, and
the wire; and
an outer lead extending outward from the sealing section;
wherein the wire is bonded to the sloping section of the inner lead.

- 2-4. (Cancelled).

5. (Original): The semiconductor device as defined in claim 1, wherein the inner lead further has a second sloping section sloping downward and outward from a higher end of the sloping section.

6. (Original): The semiconductor device as defined in claim 1, wherein the inner lead further has a portion extending in a horizontal direction and connected to the outer lead.

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7. (Previously Presented): The semiconductor device as defined in claim 1, wherein a bonding position between the wire and the inner lead is lower than the position of the electrode.

8. (Cancelled).

9. (Original): The semiconductor device as defined in claim 1, wherein a surface of the die pad opposite to the semiconductor chip is exposed from the sealing section.

10. (Original): A circuit board on which the semiconductor device as defined in claim 1 is mounted.

11. (Original): An electronic instrument comprising the semiconductor device as defined in claim 1.

12-20. (Cancelled).

21. (Currently Amended): A semiconductor device comprising:

an inner lead having a first sloping section sloping upward and outward, the inner lead having a second sloping section sloping downward and outward from a higher end of the first sloping section, when a surface of the die pad which the semiconductor chip is bonded faces upward;

a die pad;

a semiconductor chip having an electrode and bonded to the die pad;

a wire electrically connecting the inner lead to the electrode;

a sealing section sealing the inner lead, the semiconductor chip, and the wire; and

an outer lead extending outward from the sealing section.